


Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes evenly
- Clamshell lid

Materials:

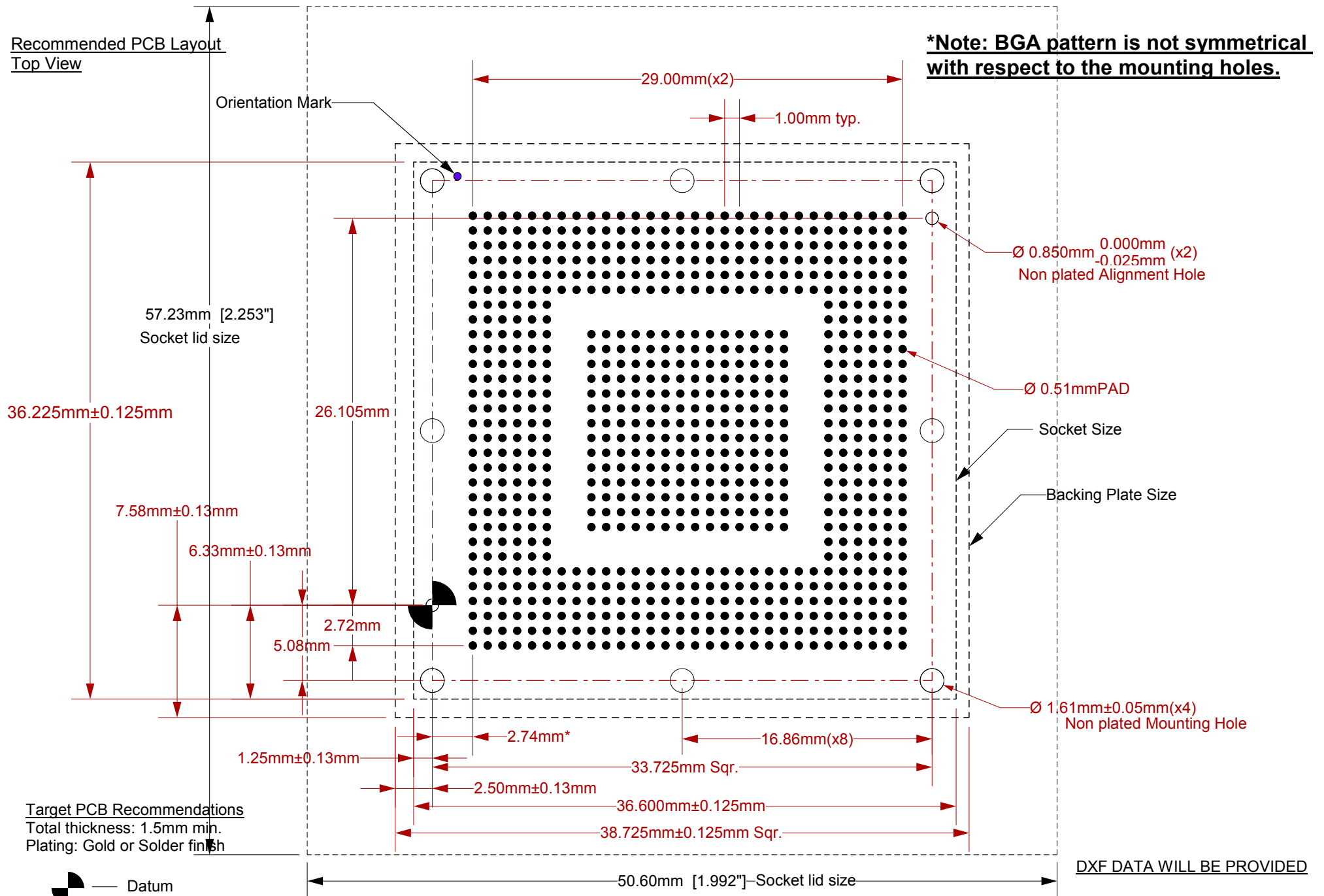
- 1 Clam Shell Lid: Black anodized 7075 Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized 7075 Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized 7075 Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized 7075 Aluminum. Height = 27 mm, Fluted Knob
- 5 Pogo Pin: Plungers - Hardened Steel/ Gold plated
Barrel - Copper Alloy/ Gold plated
Spring - Stainless Steel/ Gold wire
- 6 Pogo Pin Guides: Ultem 1000.
- 7 Socket Base Screw: Socket Head Cap Screw, Black Oxide 0-80 Thread, 5/8" long.
- 8 Backing Plate: Black anodized 7075 Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- 11 Latch: Black anodized 7075 Aluminum.


	SS-BGA772A-01 Drawing	Status: Released	Scale: 1.25:1	Rev: A
	© 2005 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 9/12/05
		File: SS-BGA772A-01 Dwg	Modified:	

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

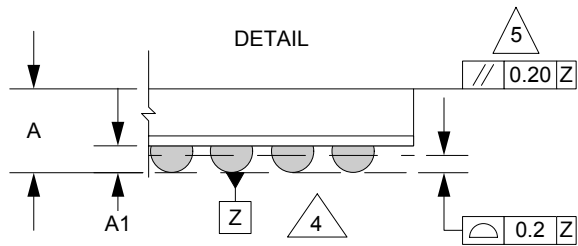
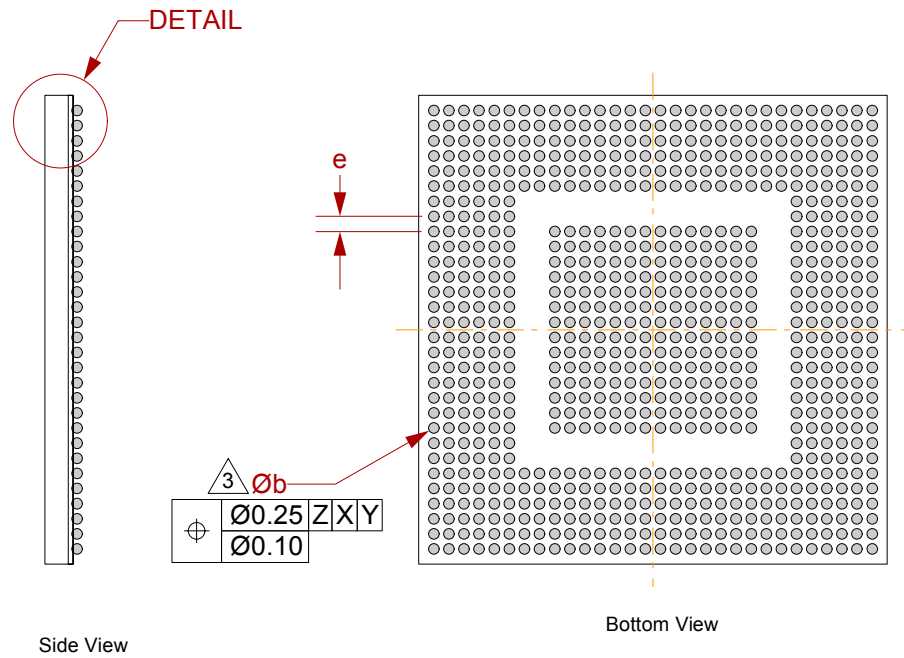
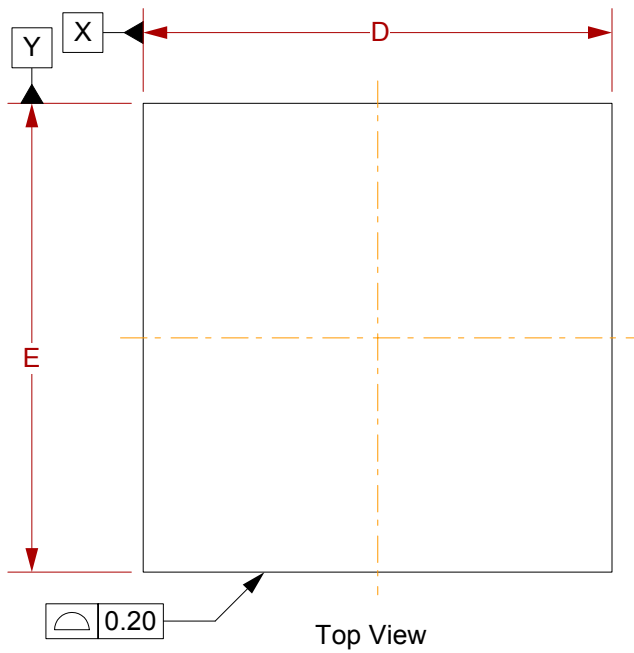
***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



	SS-BGA772A-01 Drawing	Status: Released	Scale: 3:1	Rev: A
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		File: SS-BGA772A-01 Dwg	Modified:	

Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.


Compatible BGA Spec



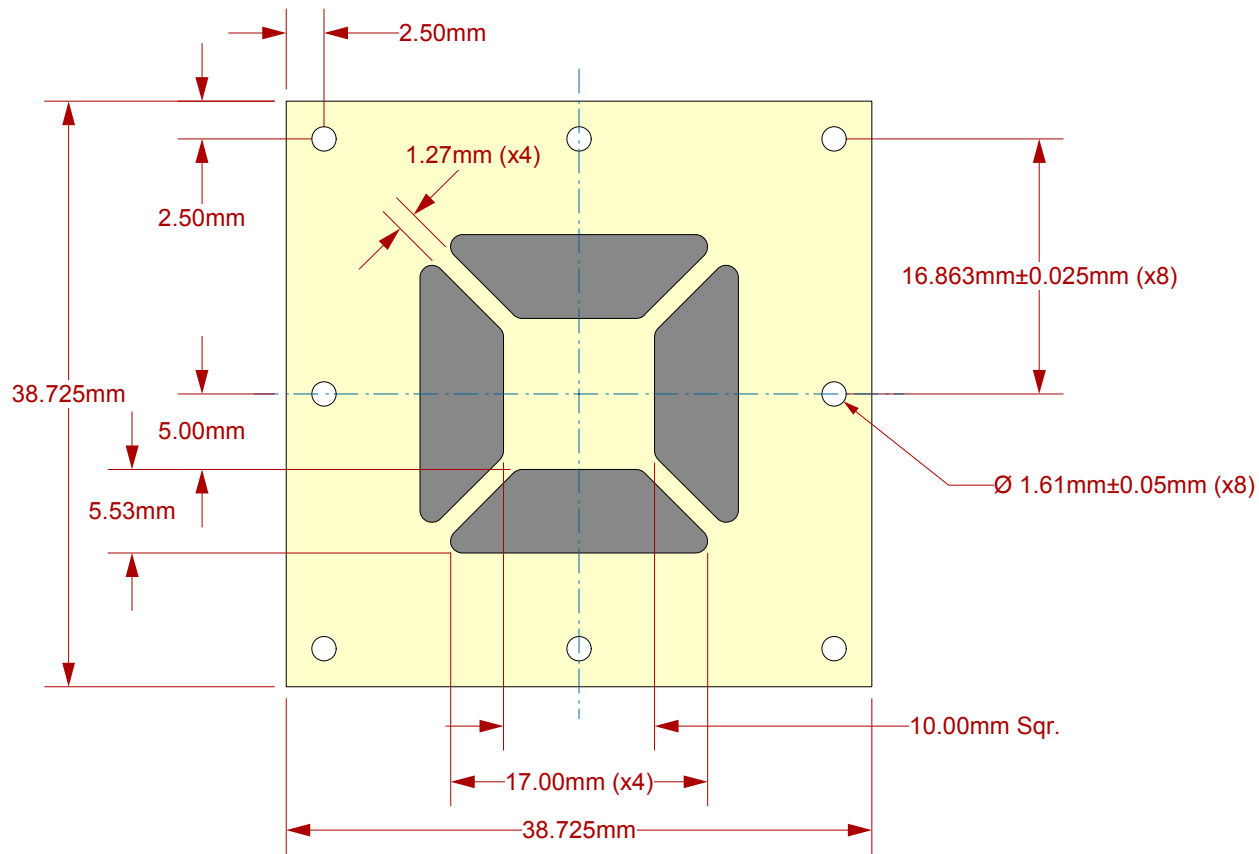
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- ③ Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - ④ Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - ⑤ Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.48
A1	0.4	0.6
b		0.70
D	31.00 BSC	
E	31.00 BSC	
e	1.0 BSC	

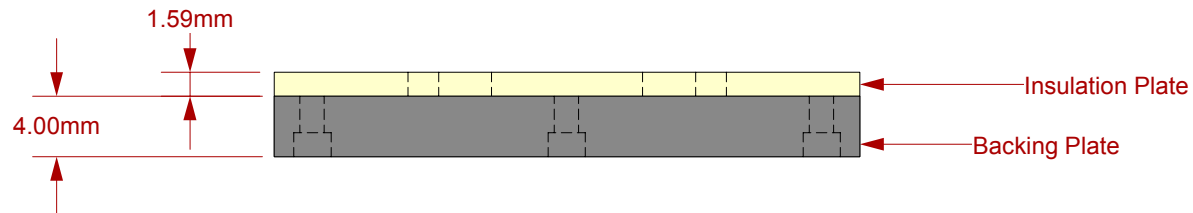
30 x 30 Array

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		File: SS-BGA772A-01 Dwg	Modified:	


Top View



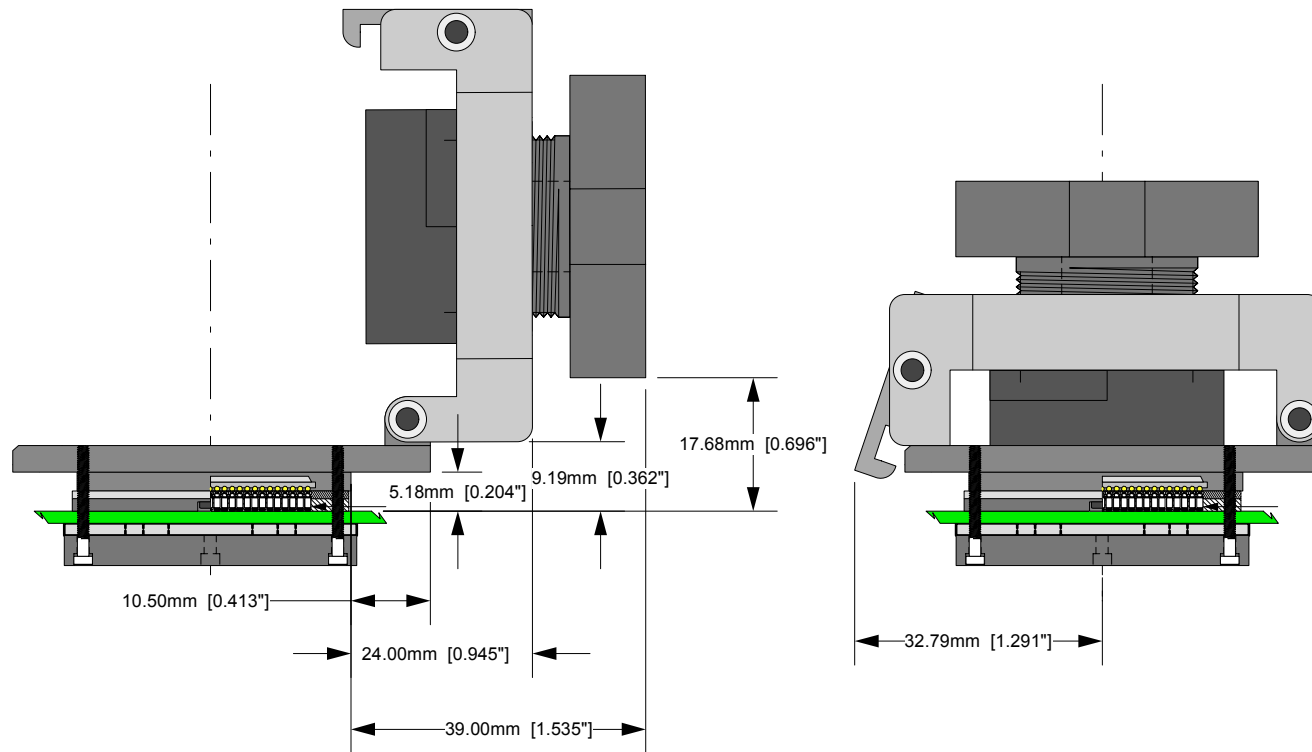
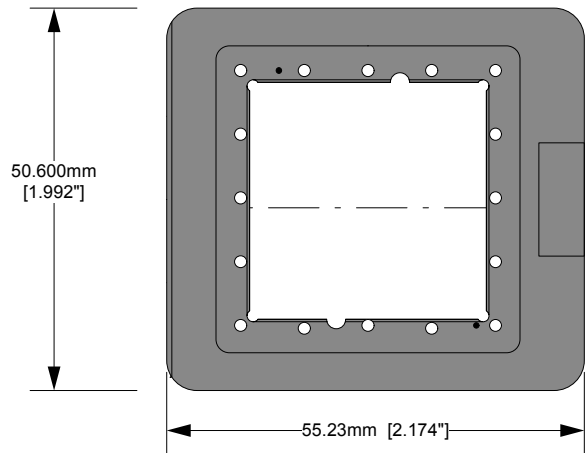
Side View




Description: Insulation Plate and Backing Plate

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		File: SS-BGA772A-01 Dwg	Modified:	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)



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			File: SS-BGA772A-01 Dwg		Modified:

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)